

Double Sided Thermally Conductive Adhesive EU-BOND150



EU-Bond150 material is designed to provide an efficient method of mounting heatsinks onto devices such as microprocessors, small electronic packages and other components, which require heatsinks.

EU-Bond150 material makes a fast and efficient thermal interface and eliminate the need for clip, clamps or any other form of mechanical fixing. The use of messy thermal compound is also eliminated.

EU-Bond150 material is available in rolls, sheets and die-cut to individual shapes.

SPECIFIC PRODUCT CHARACTERISTICS:

Features&Benefits	Configurations	Typical application
 Easy to handle Avoid use of clips and clamps Cost effective 	Sheet 300x300mmRoll 300mmx100mDie cut parts	 Microprocessor Small Electronic Packages LED Any electronic components which require heatsinks



PRODUCT PROPERIES:

Properties	Units	EU-BOND150
Composition	-	Aluminium foil coated with a thermal conductive synthtic resin adhesive on both sides
Supporting base	-	Soft aluminium
Base thickness	mm	0,060
Total thickness	mm	0,160
Adhesive	-	Synthtic resin
Adhesive strenght	N/cm	5,5
Tensile strenght	N/cm	37,5
Elongation	%	8
Thermal conductivity	W/mK	0,284
Approximate Thermal resistance	°C – in ²/W	0,45
Temperature range	°C	- 20 to 155
Adhesive coating	-	Double faced
Colour	-	White / Cream
Interliners	-	Siliconised polypropylene film

CUSTOMIZATIONS:

Die Cutting	Water Jet Cut	Plotter Cut

Our customer are reminded that they bear the responsibility for testing Euro Technologies, Srl materials for their proposed use. Due to various application possibilities and conditions which are beyond our control, customers should carry out their own tests to determine the suitability for individual applications.

We reserve the right to change technical specifications without notice and take no responsibility for errors and misprints.

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